Receipt date: 03/22/2011 10644738 - GAU: 1721 Sheet 1 of 1 INFORMATION DISCLOSURE STATEMENT SERIAL NO. ATTY DOCKET NO. FORM PTO/SB/08 A&B (modified) 10/644,738 2003 11874 U.S. DEPARTMENT OF COMMERCE APPLICANT PATENT AND TRADEMARK OFFICE Tsuyoshi NAKAMURA et al. LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary) FILING DATE GROUP August 21, 2003 1705 Date Submitted to PTO: March 22, 2011 U.S. PATENT DOCUMENTS \*EXAMINER DOCUMENT FILING DATE CLASS SUBCLASS DATE NAME INITIAL NUMBER IF APPROPRIATE AA ΑĐ AC AD AE AF  $\Delta G$ AΗ Al FOREIGN PATENT DOCUMENTS DOCUMENT COUNTRY SUBCLASS DATE CLASS NUMBER YES NO  $\mathbf{R}\Lambda$ BB BC BD BE OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.) T. Kijima et al., "Low Temperature Deposition of Bi4Ti3O12 Thin Films by MOCVD", Functional Devices Lab. Sharp Corp., CA with "Concise Explanation of the Relevance with Respect to Extended Abstracts (The 42nd Spring Meeting, 1995); The Japan Society of Applied Physics and Related Societies", 29p-D-2. H, Watanabe et al., "Development of Y1 Materials (Bi Layer Structured Ferroelectrics) Thin-Film Capacitors (II)", Olympus CB Optical Co., Ltd. \*Symetrix Co., with "Concise Explanation of the Relevance with Respect to Extended Abstracts (The 55th Autumn Meeting, 1994); The Japan Society of Applied Physics", 20p-M-19. Jun-Sung Chun et al., "Toward 0.1 µm Contact Hole Process by Using Water Soluble Organic Over-Coating Material (WASOOM); Resist Flow Technique (III); Study on WASOOM, Top Flare and Etch Characterization", Advances in Resist Technology and Processing XVIII, Proceedings of SPIE, Vol. 4345 (2001), pages 647-654. S. Satoh et al., "Electrical Properties of Bi<sub>4</sub>Ti<sub>3</sub>O<sub>12</sub> Thin Films by MOCVD", Functional Devices Lab. Sharp Corp., with "Concise Explanation of the Relevance with Respect to Extended Abstracts (The 42nd Spring Meeting, 1995); The Japan Society of Applied Physics and Related Societies", 29p-D-3. EXAMINER /Christopher Young/ (04/25/2011) DATE CONSIDERED 04/25/2011

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /CY/

<sup>\*</sup>Examiner: initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.